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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: West et al. Art Unit: 2822
Serial No.: 10/697,137 Examiner: Guerrero, M.
Filing Date: 10/30/2003 Docket No.: TI-36238
Customer No.: 23494 Conf. No.: 9756
Title: METHOD FOR IMPROVING RELIABILITY OF COPPER INTERCONNECTS

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